

Electronic Acknowledgement Receipt

EFS ID:	1006993
Application Number:	10524013
Confirmation Number:	7576
Title of Invention:	Method for manufacturing compound semiconductor wafer and compound semiconductor device
First Named Inventor:	Hisashi Yamada
Customer Number:	2292
Filer:	John Wayne Bailey/Erin Miller
Filer Authorized By:	John Wayne Bailey
Attorney Docket Number:	0152-0703PUS1
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Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		20060228ResponsetoRestrictionRequirement.pdf	85879	yes	4

	Multipart Description		
	Doc Desc	Start	End
	Transmittal letter	1	1
	Response to Election / Restriction Filed	2	4

Warnings:

Total Files Size (in bytes):

85879

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.